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## Patent Abstracts of Japan

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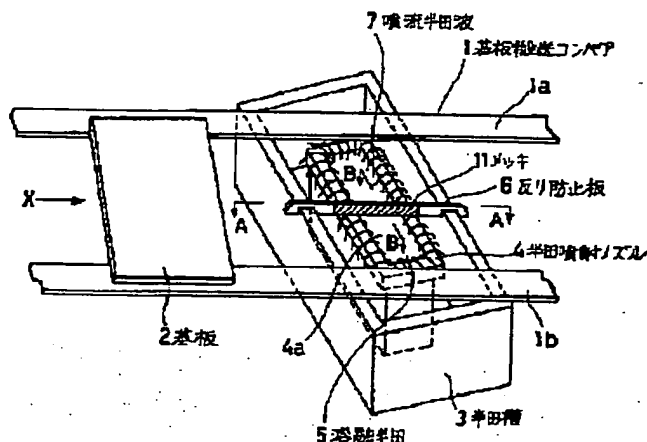
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APPLICANT : TOSHIBA CORP;

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TITLE : SOLDERING DEVICE



**ABSTRACT :** PROBLEM TO BE SOLVED: To make it possible to solder fully and evenly also to a part, on which a substrate is passed through, of a warpage prevention plate by a method wherein a plating, which has a wettability with solder, is applied to at least a part, which is dipped in a jet solder liquid, of the warpage prevention plate provided on the upper part of a solder tank.

**SOLUTION:** A preheated substrate 2 is passed through over a solder tank 3 and at this time, as roughly the center of the substrate 2 is supported by a warpage prevention plate 6, the substrate 2 is never warped in the direction under its lower part by its tare weight, heating or the like. The jet of a molten solder 5, which is jetted through solder jet nozzles 4, comes into contact with the lower surface of the substrate 2 and the molten solder 5 is adhered to a soldering position on the substrate 2. At this time, as a plating 11 having a wettability with solder is applied to a part, which is dipped in a jet solder liquid 7, of the plate 6, the liquid 7 loses its resistance to the plate 6 and the plate 6 is coated up to its upper part with the solder 5.

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